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SATA 6Gb/s 2.5" SSD Manual



The SATA SSD is a non-volatile, solid-state storage device. With its Serial ATA interface and industry-standard form factors, it is a drop in replacement for hard disk drives. The SSD delivers extremely high levels of performance, reliability and ruggedness for I/O intensive or environmentally challenging applications.

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Revision History

Date	Revision	Description	Checked by
3/16/17	A	Initial release modified from PSFS22xxxxLxxx_G	
5/31/17	B	Add VSFS22960GLIFWSME, VSFS22960GLIZMSC VSFS22960GLIZVSD VSFS22960GLIZVSCE VSFS22960GLIZVSDE	

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Ordering Information: 2.5" SSD Solid-State Drive

Part Numbers	SATA Interface	Application	Useable Capacity (GB) ¹	Temperature Range	NAND
VSFS22480GLCHWSME	SATA 6GB	Enterprise	480 GB	(0 to +70'c)	Samsung TLC VNAND (3D)
VSFS22960GLCFWSME	SATA 6GB	Enterprise	960 GB	(0 to +70'c)	Samsung TLC VNAND (3D)
VSFS22960GLIFWSME	SATA 6GB	Enterprise	960 GB	(-40 to +85'c)	Samsung TLC VNAND (3D)
VSFS22960GLIZMSC	SATA 6GB	Enterprise	960 GB	(-40 to +85'c)	Samsung MLC
VSFS22960GLIZVSD	SATA 6GB	Enterprise	960 GB	(-40 to +85'c)	Samsung MLC VNAND (3D)
VSFS22960GLIZVSCE	SATA 6GB	Enterprise	960 GB	(-40 to +85'c)	Samsung MLC VNAND (3D)
VSFS221T92LCFWSME	SATA 6GB	Enterprise	1920 GB	(0 to +70'c)	Samsung TLC VNAND (3D)

- Usable capacity based on specification LBA1-03a and level of over-provisioning applied to wear leveling, bad sectors, index tables etc.
- SSD's ship unformatted from the factory unless otherwise requested.
- 1 GB = 1,000,000,000 Byte
- One Sector = 512 Byte.
- 'y' specifies flash capacity code
- xx is a wild card to indicate customer specific BOM and/or manufacturing location
- SSD drive part numbers with an E suffix (VSxxxxxxxE) are self-encrypting drives (SED)

Enterprise SSD – An Enterprise SSD contains hardware and firmware that detect and manage power failures. This allows the drive to flush the controller cache and harden data to NAND flash. No data is lost or corrupted.

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1 General Description

1.1 FEATURES

- High-Speed 8 Channel 8 Way Architecture
- Samsung Triple 500MHz Cortex-R Core Controller
- Samsung V3 NAND Flash Memory
- Up to 2GB LPDDR3 DRAM Buffer Memory
- Serial ATA 6.0Gbps Interface
- Fully complies with Serial ATA 3.0 Standard
- ATA Security Mode feature set
- ATA Host Protected Area feature set
- Support NCQ (Up to 32 depth) Command Set
- Support TRIM Command
- Asynchronous Signal Recovery
- End-to-End Data Protection
- AES 256-bit Encryption (SED)
- RoHS Compliant

1.2 DRIVE CONFIGURATION

- Form Factor 2.5"
- Interface SATA 6.0 Gbps
- Buffer DRAM Size 512 Megabytes
- Bytes per Sector 512 Bytes

1.3 PERFORMANCE SPECIFICATIONS²

- Data Transfer Rate
 - Sequential Read (128KB) V3(TLC)/V2(MLC) Up to 520/510 MB/s
 - Sequential Write (128KB) V3(TLC)/V2(MLC) Up to 485/485 MB/s
 - Random Read (4KB) V3(TLC)/V2(MLC) Up to 97/95 KIOPS
 - Random Write (4KB) V3(TLC)/V2(MLC) Up to 29/28 KIOPS
- IOPS Consistency (Read/Write @4KB) 99% / 97%
- Average Latency (Read/Write @4KB, QD32 Avg.) 100 us / 35 us
- Quality of Service(99.99%)
 - Read (4KB, QD=1) V3(TLC)/V2(MLC) 0.14/0.16 ms
 - Write (4KB, QD=1) V3(TLC)/V2(MLC) 0.12/0.15 ms
 - Read (4KB, QD=32) V3(TLC)/V2(MLC) 0.7/0.7 ms
 - Write (4KB, QD=32) V3(TLC)/V2(MLC) 2.8/3.0 ms

1.4 RELIABILITY SPECIFICATIONS

- Non-recoverable Read Error 1 sector per 10¹⁷ bits read
- MTBF 2,000,000 hours

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1.5 ENVIRONMENTAL SPECIFICATIONS

- Temperature
 - Operating³ 0 ~ 70 °C
 - Non-operating -40 ~ 85 °C
- Humidity (on-condensing)
 - Non-operating 5 ~ 95 %
- Linear Shock (1/2 sine pulse)
 - Non-operating, 0.5ms 1,500 G
- Vibration (20min /axis on 3 axes)
 - Non-Operating (10 ~ 2,000 Hz, Sweep Sine) 20 G

1.6 POWER REQUIREMENTS

- Supply Voltage +5V ± 5%
- Voltage Ripple/Noise (Max.) 100 mV p-p
- Active⁴ (Read) V3(TLC)/V2(MLC) 2.4 / 2.5 W RMS
- Active (Write) V3(TLC)/V2(MLC) 3.1 / 3.0 W RMS
- Idle⁵ (Typical) V3(TLC)/V2(MLC) 1.3 / 1.4 W

1.7 PHYSICAL DIMENSION

- Width 100.20 ± 0.25 mm
- Depth 69.85 ± 0.25 mm
- Height 6.80 ± 0.20 mm
- Weight Up to 60 g

NOTES: Specifications are subject to change without notice.

- 1) 1MB = 1,000,000 Bytes, 1GB = 1,000,000,000 Bytes, Unformatted Capacity. User accessible capacity may vary depending on operating environment and formatting.
- 2) Performance measured using IOMeter 2006 with queue depth 32. Measurements are performed on whole LBA range. Write cache enabled. Performance varies on capacity
- 3) Tc : Case Temperature
- 4) Active Read power is measured on 4 KB random read with 1920 GB density. Active Write power is measured on 128 KB sequential write with 1920 GB density.
- 5) Idle power is measured on 1920 GB density with DIPM off.

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2 Mechanical Specification

Table 2-1: Physical Dimensions and Weight

Capacity (GB)	Height (mm)	Width (mm)	Length (mm)	Weight (gram)
120 / 240 / 480 / 960 / 1,920	6.80 ± 0.20	69.85 ± 0.25	100.20 ± 0.25	60 g

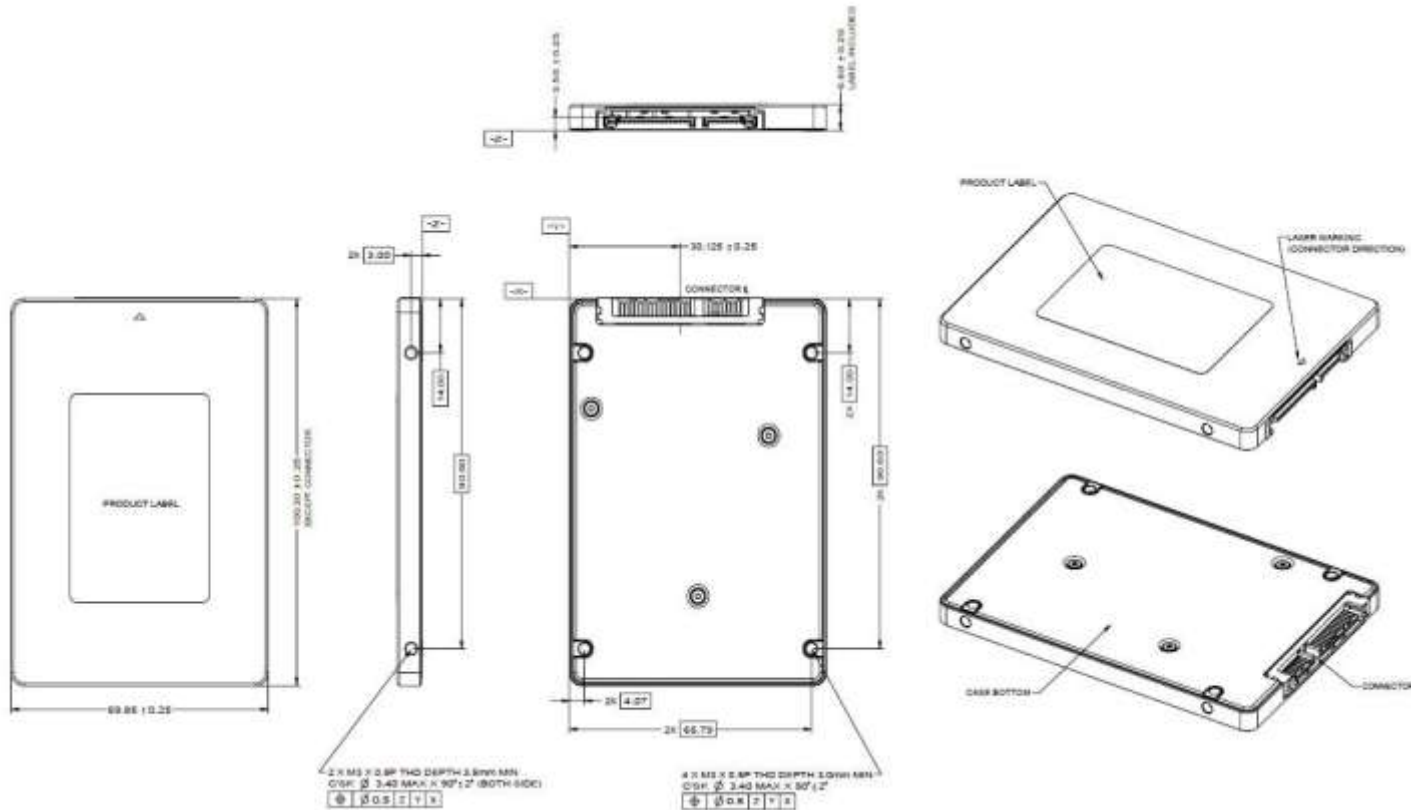


Figure 2-1: Physical Dimension

3 Product Specifications

3.1 System Interface and Configuration

- Burst read / write rate is 600 MB/sec (6 Gb/s)
- Fully compatible with ATA/ATAPI-7 Standard
- Compatible with ATA/ATAPI-8 Mandatory Command

3.2 System Performance

Table 3-1: Sequential Read / Write and Sustained Random Read / Write Performance¹

Read / Write	120 GB	240 GB	480 GB	960 GB	1,920 GB
Sequential Read Sector (128 KB) V3(TLC)/V2(MLC)	500/na MB/s	520/410 MB/s	520/510 MB/s	520/510 MB/s	520/510 MB/s
Sequential Write Sector (128 KB) V3(TLC)/V2(MLC)	460/na MB/s	485/450 MB/s	485/485 MB/s	485/485 MB/s	485/485 MB/s
Random Read IOPS (8 KB) V3(TLC)/V2(MLC)	57K/na IOPS	57K/55K IOPS	57K/55K IOPS	57K/55K IOPS	57K/55K IOPS
Random Write IOPS (8 KB) V3(TLC)/V2(MLC)	6K/na IOPS	10K/5K IOPS	13K/9K IOPS	14K/12K IOPS	14K/13K IOPS
Random Read IOPS (4 KB) V3(TLC)/V2(MLC)	97K/na IOPS	97K/90K IOPS	97K/95K IOPS	97K/95K IOPS	97K/95K IOPS
Random Write IOPS (4 KB) V3(TLC)/V2(MLC)	12K/na IOPS	20K/10K IOPS	26K/19K IOPS	28K/25K IOPS	29K/28K IOPS

NOTES:

1. Actual performance may vary depending on use conditions and environment.
Performance measured using IOMeter 2006 with queue depth 32, C216 Intel SATA 6G port.
- 2) Measurements are performed on whole LBA range.
- 3) Write cache enabled.
- 4) 1 MB/sec = 1,048,576 bytes/sec was used in sequential performance.

3.3 Drive Capacity

Table 3-2: User Capacity and Addressable Sectors^{1, 2}

	120 GB	240 GB	480 GB	960 GB	1,920 GB
User-Addressable Sectors	234,441,648	468,862,128	937,703,088	1,875,385,008	3,750,748,848
Bytes per Sector	512 Bytes				

NOTE:

1. Megabyte (MB) = 1 Million bytes; 1 Gigabyte (GB) = 1 Billion bytes
2. Actual usable capacity may be less (due to formatting, partitioning, operating system, applications or otherwise).

3.4 Operating Voltage

Table 3-3: Operating Voltage

Item	Requirements
Allowable voltage	5.0 V + 5%
Allowable noise / ripple	100 mV p-p or less
Inrush Current ¹ V3(TLC)/V2(MLC)	1.0A, <1sec / 1.2A, <1sec

NOTE:

1. The measurement value of inrush current is also compatible with the standard specification of “Enterprise SSD Form Factor Version 1.0a” released by SSD Form Factor Working Group.

3.5 System Power Consumption

Table 3-4: Power Consumption

Read/Write	120 GB	240 GB	480 GB	960 GB	1,920 GB
Active Write ¹ - RMS Average V3(TLC)/V2(MLC)	2.5/na Watt	2.7/2.5 Watt	2.8/2.8 Watt	2.9/2.9 Watt	3.1/ 3.0 Watt
Active Read ² - RMS Average V3(TLC)/V2(MLC)	2.2/na Watt	2.2/2.0 Watt	2.2/2.3 Watt	2.2/2.4 Watt	2.4/2.5 Watt
Idle ³ V3(TLC)/V2(MLC)	1.3/na Watt	1.3/1.3 Watt	1.3/1.3 Watt	1.3/1.3 Watt	1.3/1.4 Watt

NOTES:

1. Active Write power is measured on 128 KB sequential write.
2. Active Read power is measured on 4 KB random read.
3. Idle power is measured with DIPM off.

3.6 System Reliability

Table 3-5: TBW, MTBF, UBER Specifications

	120 GB	240 GB	480 GB	960 GB	1,920 GB
TBW ¹ V3(TLC)	170 TB	350 TB	700 TB	1,400TB	2,800 TB
TBW ¹ V2(MLC)	na	1314 TB	2628 TB	5256 TB	10,512 TB
MTBF ²	2,000,000 Hours				
UBER ³	1 sector per 10 ¹⁷ bits read				
Data Retention ⁴	3months				
DWPD ⁵ V3(TLC)	0.8 (5years)	0.8 (5years)	0.8 (5years)	0.8 (5years)	0.8 (5years)
DWPD ⁵ V2(MLC)	3 (5years)	3 (5years)	3 (5years)	3 (5years)	3 (5years)

NOTES:

1. TBW is measured while running 100 % random 4 KB writes across the entire SSD.
2. MTBF is Mean Time Between Failure. As same word, annual failure ratio is 0.438%.
3. Uncorrectable Bit Error Rate (UBER) is a metric for the rate of occurrence of data errors, equal to the number of data errors per bits read as specified in the JESD218 document of JEDEC standard. For the enterprise application, JEDEC recommends that UBER shall be below 10-16.
4. Data retention was measured by assuming that SSD reaches the maximum rated endurance at 40C in power-off state.
5. DWPD is Drive Write Per Day

3.7 Environmental Specifications

Table 3-6: Environmental Specifications

Features	Operating	Non-Operating
Commercial Temperature ¹	0 °C to 70 °C	-40 °C to 85 °C
Industrial Temperature ¹	-40 °C to 85 °C	-40 °C to 85 °C
Temperature Gradient	30 °C /Hr	30 °C /Hr
Humidity ²	5 % to 95 %, non-condensing	
Shock ³	1500 G, duration 0.5 ms, Half Sine Wave	
Vibration ⁴	20G, 10 - 2000 Hz, 20 min/axis (X,Y,Z)	

NOTES:

1. Temperature specification is following JEDEC standard; Expressed temperature must be measured right on the case.
2. Humidity is measured in non-condensing.
3. Test condition for shock: 0.5 ms duration with half sine wave
4. Test condition for vibration: 10 Hz to 2,000 Hz, 15 mins/axis on 3 axis

3.8 IOPS Consistency

Table 3-7: IOPS Consistency

IOPS Consistency ^{1, 2}	120 GB	240 GB	480 GB	960 GB	1,920 GB
Random Read	99%	99%	99%	99%	99%
Random Write	93%	97%	97%	97%	97%

NOTES:

1. IOPS consistency measured using (4 KB) FIO with queue depth 32.

2. IOPS Consistency (%) = (99.9% IOPS) / (Average IOPS) x 100

3.9 Latency

Table 3-8: Latency

Latency1	120 GB	240 GB	480 GB	960 GB	1,920 GB
Read V3(TLC)/V2(MLC)	100/na us	100/110 us	100/110 us	100/110 us	100/110 us
Write V3(TLC)/V2(MLC)	66/na us	38/85 us	35/50 us	35/35 us	35/35 us

NOTE:

1. Latency is measured using (4 KB)FIO with queue depth 1 on 4KB random and write.

3.10 Quality of Service (QoS)

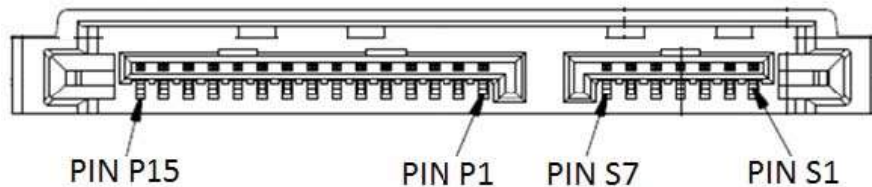
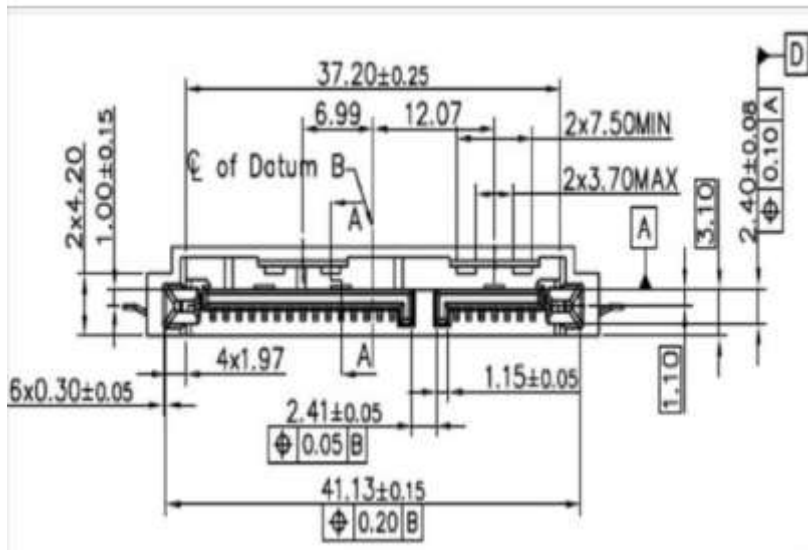
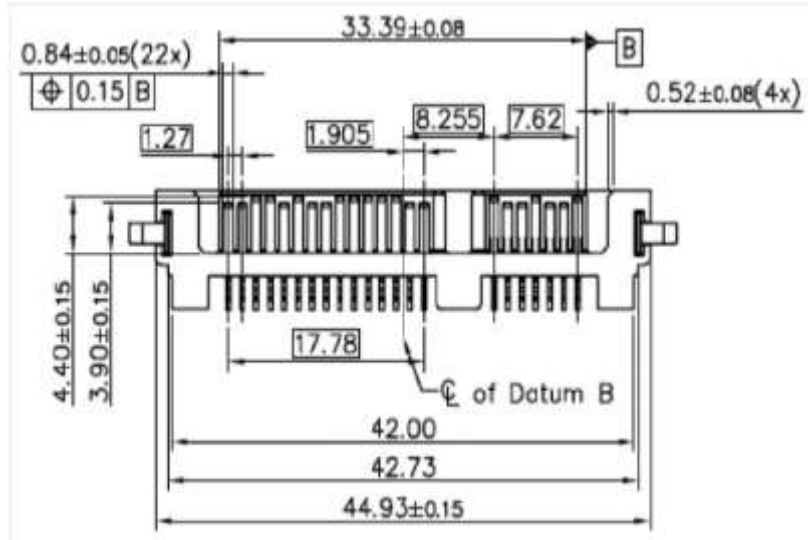
Quality of Service (99%) ^{1, 2}	120 GB	240 GB	480 GB	960 GB	1,920 GB
Read (4 KB, QD=1) V3(TLC)/V2(MLC)	0.12/na ms	0.12/0.13 ms	0.12/0.13 ms	0.12/0.13 ms	0.12/0.13 ms
Write (4 KB, QD=1) V3(TLC)/V2(MLC)	0.12/na ms	0.12/0.13 ms	0.12/0.12 ms	0.12/0.12 ms	0.12/0.12 ms
Read (4 KB, QD=32) V3(TLC)/V2(MLC)	0.12/na ms	0.5/1.0 ms	0.5/0.6 ms	0.5/0.6 ms	0.5/0.6 ms
Write (4 KB, QD=32) V3(TLC)/V2(MLC)	0.12/na ms	2.7/4.0 ms	2.5/3.0 ms	2.4/2.7 ms	2.3/2.5 ms
Quality of Service (99.99%) ^{1, 2}	120 GB	240 GB	480 GB	960 GB	1,920 GB
Read (4 KB, QD=1) V3(TLC)/V2(MLC)	0.12/na ms	0.14/0.16 ms	0.14/0.16 ms	0.14/0.16 ms	0.14/0.16 ms
Write (4 KB, QD=1) V3(TLC)/V2(MLC)	0.12/na ms	0.12/0.16 ms	0.12/0.15 ms	0.12/0.15 ms	0.12/0.15 ms
Read (4 KB, QD=32) V3(TLC)/V2(MLC)	1.0/na ms	0.7/1.4 ms	0.7/0.7 ms	0.7/0.7 ms	0.7/0.7 ms
Write (4 KB, QD=32) V3(TLC)/V2(MLC)	3.8/na ms	2.8/5.3 ms	2.8/3.0 ms	2.8/3.0 ms	2.0/3.0 ms

NOTES:

1. QoS is measured using Fio 2.1.3 (99 and 99.99%) in Linux RHEL 6.5 (Kernel 2.6.32) with queue depth 1, 32 on 4KB random read and write.
2. QoS is measured as the maximum round-trip time taken for 99 and 99.99% of commands to host.

4 Electrical Interface Specification

4.1 Serial ATA Interface Connector



4.2 Pin Assignments

Table 4-1: Pin Assignments

Word	No.	Plug Connector pin definition	
Signal	S1	GND	2nd mate
	S2	A +	Differential signal A from Phy
	S3	A -	
	S4	GND	2nd mate
	S5	B -	Differential signal B from Phy
	S6	B +	
	S7	GND	2nd mate
Key and spacing separate signal and power segments			
Power	P1	V33	3.3 V power (Unused)
	P2	V33	3.3 V power (Unused)
	P3	V33	3.3 V power, pre-charge, 2nd mate (Unused)
	P4	GND	1st mate
	P5	GND	2nd mate
	P6	GND	2nd mate
	P7	V5	5 V power, pre-charge, 2nd mate
	P8	V5	5 V power
	P9	V5	5 V power
	P10	GND	2nd mate
	P11	DAS / DSS	Device Activity Signal / Disable Staggered Spin-up
	P12	GND	1st mate
	P13	V12	12 V power, pre-charge, 2nd mate (Unused)
	P14	V12	12 V power (Unused)
	P15	V12	12 V power (Unused)

NOTE:

1. Uses 5 V power only. 3.3 V and 12 V power are not used
- 2) Pin11, Device Activity Signal States (DAS Pin is toggle when host initiated Background job)

Device State	Pin Out
Active	Toggle
Idle	High

5 Command Descriptions

5.1 Supported ATA Commands

Table 5-1: Supported ATA Commands Summary

Command Name	Command Code (Hex)	Command Name	Command Code (Hex)
CHECK POWER MODE	E5h / 98h	SET MAX ADDRESS EXT	37h
DEVICE CONFIGURATION	B1h	SET MULTIPLE MODE	C6h
DOWNLOAD MICROCODE	92h	SLEEP	E6h / 99h
DOWNLOAD MICROCODE DMA	93h	S.M.A.R.T.	B0h
EXECUTE DEVICE DIAGNOSTIC	90h	STANDBY	E2h / 96h
FLUSH CACHE	E7h	STANDBY IMMEDIATE	E0h / 94h
FLUSH CACHE EXT	EAh	TRIM	06h
IDENTIFY DEVICE	ECh	WRITE BUFFER	E8h
IDLE	E3h / 97h	WRITE BUFFER DMA	EBh
IDLE IMMEDIATE	E1h / 95h	WRITE DMA	CAh
INITIALIZE DEVICE PARAMETERS	91h	WRITE DMA (w/o retry)	CBh
NOP	00h	WRITE DMA EXT	35h
READ BUFFER	E4h	WRITE DMA FUA EXT	3Dh
READ BUFFER DMA	E9h	WRITE FPDMA QUEUED	61h
READ DMA	C8h	WRITE LOG DMA EXT	57h
READ DMA (w/o retry)	C9h	WRITE LOG EXT	3Fh
READ DMA EXT	25h	WRITE MULTIPLE	C5h
READ FPDMA QUEUED	60h	WRITE MULTIPLE EXT	39h
READ LOG DMA EXT	47h	WRITE MULTIPLE FUA EXT	CEh
READ LOG EXT	2Fh	WRITE SECTORS	30h
READ MULTIPLE	C4h	WRITE SECTORS (w/o retry)	31h
READ MULTIPLE EXT	29h	WRITE SECTORS EXT	34h
READ NATIVE MAX ADDRESS	27h	WRITE UNCORRECTABLE EXT	45h
READ NATIVE MAX ADDRESS EXT	F8h	Set Date N Time	77h
READ SECTORS	20h		
READ SECTORS (w/o retry)	21h		
READ SECTORS EXT	24h		
READ VERIFY SECTORS	40h		
READ VERIFY SECTORS (w/o retry)	41h		
READ VERIFY SECTORS EXT	42h		
RECALIBRATE	10h		
RECEIVE FPDMA QUEUED	65h		

Command Name	Command Code (Hex)	Command Name	Command Code (Hex)
SANITIZE DEVICE	B4h		
SECURITY DISABLE PASSWORD	F6h		
SECURITY ERASE PREPARE	F3h		
SECURITY ERASE UNIT	F4h		
SECURITY FREEZE LOCK	F5h		
SECURITY SET PASSWORD	F1h		
SECURITY UNLOCK	F2h		
SEEK	70h		
SEND FPDMA QUEUED	64h		
SET FEATURES	EFh		
SET MAX ADDRESS	F9h		

5.2 Individual Attribute Data Structure

The following defines the 12 bytes that make up the information for each Attribute entry in the Device Attribute Data Structure.

Table 5-2: Attribute Entry in Device Attribute Data Structure

Byte	Descriptions
0	Attribute ID number 01-FFh
1-2	Status flag bit 0 (pre-failure / advisory bit) bit 0 = 0: If attribute value is less than the threshold, the drive is in advisory condition. Product life period may expired. bit 0 = 1: If attribute value is less than the threshold, the drive is in pre-failure condition. The drive may have failure. bit 1 (on-line data collection bit) bit 1 = 0: Attribute value will be changed during off-line data collection operation. bit 1 = 1: Attribute value will be changed during normal operation. bit 2 (Performance Attribute bit) bit 3 (Error rate Attribute bit) bit 4 (Event Count Attribute bit) bit 5 (Self-Preserving Attribute bit) bit 6 - 15 Reserved
3	Attribute value 01h - FDh *1 00h, FEh, FFh = Not in use 01h = Minimum value 64h = Initial value Fdh = Maximum value
4	Worst Ever normalized Attribute Value (valid values from 01h - FEh)
5 - 10	Raw Attribute Value Attribute specific raw data (FFFFFFh - reserved as saturated value)
11	Reserved (00h)
*1 For ID = 199 CRC Error Count	

The device supports following Attribute ID Numbers.

Table 5-3: S.M.A.R.T. Attributes¹

ID (Word)	Attribute Name	Status Flag	Threshold (%)
5	Reallocated Sector Count	110011	10
9	Power-on Hours	110010	-
12	Power-on Count	110010	-
177	Wear Leveling Count	010011	5
179	Used Reserved Block Count (total)	010011	10
180	Unused Reserved Block Count (total)	010011	10
181	Program Fail Count (total)	110010	-
182	Erase Fail Count (total)	110010	-
183	Runtime Bad Count (total)	010011	10
184	End to End Error data path Error Count	110011	97
187	Uncorrectable Error Count	110010	-
190	Air Flow Temperature	110010	-
195	ECC Error Rate	011010	-
197	Pending Sector Count	110010	-
199	CRC Error Count	111110	-
202	SSD Mode Status	110011	10
235	Power Recovery Count	010010	-
241	Total LBA Written	110010	-
242	Total LBA Read	110010	-
243	SATA Downshift Control	110010	-
244	Thermal Throttle Status	110010	-
245	Timed Workload Media Wear	110010	-
246	Timed Workload Host Read / Write Ratio	110010	-
247	Timed Workload Timer	110010	-
251	NAND Writes	110010	-

Note

1. Any nonzero value in the Attribute ID Number indicates an active attribute.

6 SPOR Specification (Sudden Power Off and Recovery)

6.1 Data Recovery in Sudden Power Off

If power interruption is detected, SSD dumps all cached user data and meta data to NAND Flash. SSD could protect even the user data in DRAM from sudden power off while SSD is used with cache on. Commonly, data is protected all of the operation period.

6.2 Time to Ready Sequence

In normal power-off recovery status, SSD needs less than 3 seconds to reach operating mode where SSD works perfectly with cache-on state. SSD is ready to respond Identify Device command during FTL OPEN. When the sudden power-off occurs, the user data in DRAM will be dumped into to NAND Flash using the stored power in the capacitor. In sudden power-off recovery condition, mapping data will be loaded or the FTL meta data be rebuilt perfectly for initial max. 18 seconds. During this period, Identify Device command is still supported. It is called SPOR (Sudden Power Off and Recovery).

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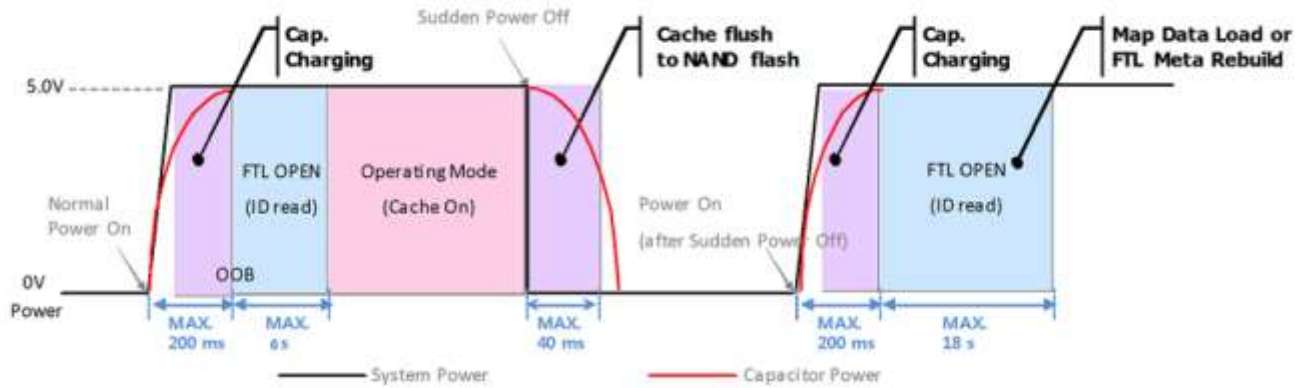


Figure 6-1: Time to Ready Sequence (V3 TLC NAND)

Table 6-1: Device Ready Time for Normal Read/Write after Sudden Power off (V3 TLC NAND)

	120 GB	240 GB	480 GB	960 GB	1,920 GB
Max. Open Time (sec)	6	6	6	9	18

Figure 6-2: Time to Ready Sequence (V2 MLC NAND)

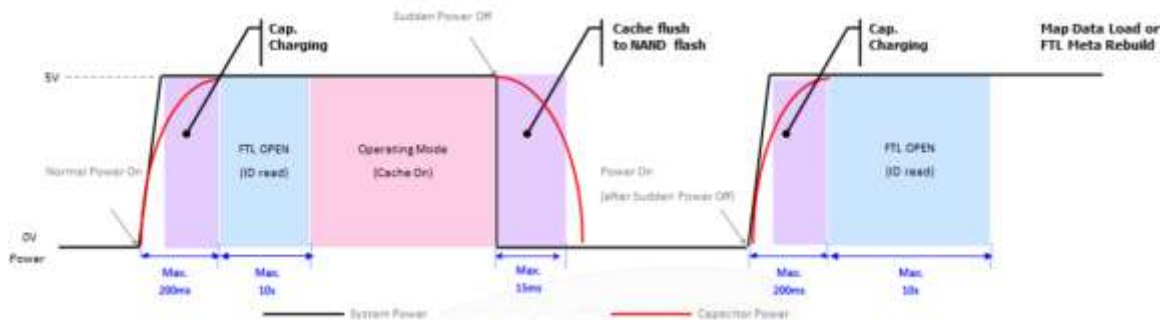


Table 6-2: Device Ready Time for Normal Read/Write after Sudden Power off (V2 MLC NAND)

	120 GB	240 GB	480 GB	960 GB	1,920 GB
Max. Open Time (sec)	na	10	10	10	10

7 Data Security

7.1 Encryption

The SSD drives based on VSxxxxxxxE part numbers are self-encrypting drives (SED), with a bulk data encryption feature that provides automatic hardware-based data security and enhanced secure erase capability.

A self-encrypting drive, scrambles data using a data encryption key as it is written to the drive and then descrambles it with the key as it is retrieved. This gives the user the highest level of data protection available and provides a fast erase simply by deleting the encryption key, eliminating the need for time consuming data-overwrite. Data on the drive is instantly rendered unreadable.

The SED SSD drives support the following security features:

- AES 256 on the fly support
- ATA Secure Erase
- Class 0 (ATA Password)

8 Product Compliance

8.1 Product Regulatory Compliance and Certifications

Table 8-1: Standards Reference

Category	Certification
CE	Comunaute Europeenne
BSMI	Bureau of Standards, Metrology and Inspection
KCC	KCC Korea Communications commission
VCCI	Voluntary Control Council for Interference
C-Tick	Radio Telecommunication Labeling
FCC	Federal Communications Commission
IC	Industry Canada
UL	Underwriters Laboratories Inc.
TUV	Technischer Überwachungs Verein e.V.
CB	Scheme of the IECEE for Mutual Recognition of Test Certificates for Electrical Equipment



Caution :

Any changes or modifications in construction of this device which are not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

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NOTE:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures: - Reorient or relocate the receiving antenna. - Increase the separation between the equipment and receiver. - Connect the equipment into an outlet on a circuit different from that to which the receiver is connected. - Consult the dealer or an experienced radio/TV technician for help. Modifications not expressly approved by the manufacturer could void the user's authority to operate the equipment under FCC rules.

Modifications not expressly approved by the manufacturer could void the user's authority to operate the equipment under FCC rules.



1. 기자재 명칭 : SSD (Solid State Drive)
2. 모델명(Model): 라벨 별도 표기
3. 제조연월 : 라벨 별도 표기
4. 제조자 : 삼성전자(주)
5. 제조국가 : 대한민국
6. 상호명 : 삼성전자(주)

Industry Canada ICES-003 Compliance Label:
CAN ICES-3 (B)/NMB-3(B)

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9 Identify Device Data

9.1 Identify Device Data

The table below lists the sector data that will be returned by the SSD upon an IDENTIFY DEVICE command.

Table 9-1: List of Device Identification

Word	480 GB	960 GB	1,920 GB	3,840 GB	Description
0	0040h	0040h	0040h	0040h	General Information
1	3FFFh	3FFFh	3FFFh	3FFFh	Obsolete
2	C837h	C837h	C837h	C837h	Specific Configuration
3	0010h	0010h	0010h	0010h	Obsolete
4 - 5	0000h	0000h	0000h	0000h	Retired
6	003Fh	003Fh	003Fh	003Fh	Obsolete
7 - 8	0000h	0000h	0000h	0000h	Reserved for the Compact Flash Association
9	0000h	0000h	0000h	0000h	Retired
10 - 19	XXXXh	XXXXh	XXXXh	XXXXh	Serial Number (ATA string)
20 - 21	0000h	0000h	0000h	0000h	Reserved
22	0000h	0000h	0000h	0000h	Obsolete
23 - 26	XXXXh	XXXXh	XXXXh	XXXXh	Firmware Revision (ATA string)
27 - 46	XXXXh	XXXXh	XXXXh	XXXXh	Model Number
47	8010h	8010h	8010h	8010h	Read / Write Multiple Support
48	4000h	4000h	4000h	4000h	Trusted Computing Feature Set Options
49	2F00h	2F00h	2F00h	2F00h	Capabilities
50	4000h	4000h	4000h	4000h	Capabilities
51 - 52	0200h	0200h	0200h	0200h	Obsolete
53	0007h	0007h	0007h	0007h	Field Validity
54	3FFFh	3FFFh	3FFFh	3FFFh	Obsolete
55	0010h	0010h	0010h	0010h	Obsolete
56	003Fh	003Fh	003Fh	003Fh	Obsolete
57	FC10h	FC10h	FC10h	FC10h	Obsolete
58	00FBh	00FBh	00FBh	00FBh	
59	D110h	D110h	D110h	D110h	Multiple Logical Setting
60	FFFFh	FFFFh	FFFFh	FFFFh	Total Number of User Addressable Logical Sectors for 28-bit Commands
61	0FFFh	0FFFh	0FFFh	0FFFh	
62	0000h	0000h	0000h	0000h	Obsolete